Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **OUT 1**
2. **IN 1-**
3. **IN 1+**
4. **VCC-**
5. **IN 2+**
6. **IN 2-**
7. **OUT 2**
8. **VCC+**

**.067”**

**.046”**

**2 1 8 7**

**3 4 5 6**

**EXU062A**

**MASK**

**REF**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: Vcc- or FLOATING**

**Mask Ref: EXU062A**

**APPROVED BY: DK DIE SIZE .046” X .067” DATE: 4/27/23**

**MFG: TEXAS INSTRUMENTS THICKNESS .015” P/N: TL062**

**DG 10.1.2**

#### Rev B, 7/19/02